## MBRB20200CTG, SBRB20200CTT4G

## Switch-mode Power Rectifier

## **Dual Schottky Rectifier**

This device uses the Schottky Barrier technology with a platinum barrier metal. This state-of-the-art device is designed for use in high frequency switching power supplies and converters with up to 48 V outputs. They block up to 200 V and offer improved Schottky performance at frequencies from 250 kHz to 5.0 MHz.

#### **Features**

- 200 V Blocking Voltage
- Low Forward Voltage Drop
- Guardring for Stress Protection and High dv/dt Capability (10,000 V/μs)
- Dual Diode Construction Terminals 1 and 3 Must be Connected for Parallel Operation at Full Rating
- AEC-Q101 Qualified and PPAP Capable
- SBRB Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- All Packages are Pb-Free\*

#### **Mechanical Characteristics:**

- Case: Epoxy, Molded, Epoxy Meets UL 94 V-0
- Weight: 1.7 Grams (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Device Meets MSL1 Requirements
- ESD Rating:
  - ♦ Human Body Model = 3B
  - ♦ Machine Model = C



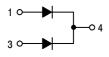
#### ON Semiconductor®

http://onsemi.com

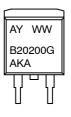
## SCHOTTKY BARRIER RECTIFIER 20 AMPERES, 200 V



D<sup>2</sup>PAK CASE 418B



#### **MARKING DIAGRAM**



A = Assembly Location

Y = Year

WW = Work Week

B20200 = Device Code

G = Pb-Free Package

AKA = Diode Polarity

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

### MBRB20200CTG, SBRB20200CTT4G

#### MAXIMUM RATINGS (Per Leg)

| Rating   | Symbol   | Value       | Unit |
|--|--|-------------|------|
| Peak Repetitive Reverse Voltage<br>Working Peak Reverse Voltage<br>DC Blocking Voltage                                 | V <sub>RRM</sub><br>V <sub>RWM</sub><br>V <sub>R</sub> | 200         | V    |
| Average Rectified Forward Current (At Rated $V_R$ , $T_C$ = 134°C)  Per Leg  Per Device                                | I <sub>F(AV)</sub>                                     | 10<br>20    | A    |
| Peak Repetitive Forward Current<br>(At Rated V <sub>R</sub> , Square Wave, 20 kHz, T <sub>C</sub> = +137°C)<br>Per Leg | I <sub>FRM</sub>                                       | 20          | А    |
| Nonrepetitive Peak Surge Current<br>(Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)             | I <sub>FSM</sub>                                       | 150         | Α    |
| Peak Repetitive Reverse Surge Current (2.0 μs, 1.0 kHz)  | I <sub>RRM</sub>                                       | 1.0         | Α    |
| Storage Temperature Range  | T <sub>stg</sub>                                       | -65 to +175 | °C   |
| Operating Junction Temperature   | T <sub>J</sub>   | -65 to +150 | °C   |
| Voltage Rate of Change (Rated V <sub>R</sub> )   | dv/dt  | 10,000      | V/μs |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

#### THERMAL CHARACTERISTICS (Per Leg)

| Characteristic                       | Symbol | Value | Unit |
|--------------------------------------|--------|-------|------|
| Thermal Resistance, Junction-to-Case |        | 2.0   | °C/W |

#### **ELECTRICAL CHARACTERISTICS** (Per Leg)

| Characteristic   | Symbol         | Value                    | Unit |
|--|----------------|--------------------------|------|
| Maximum Instantaneous Forward Voltage (Note 1) ( $I_F = 10 \text{ A}$ , $T_C = 25^{\circ}\text{C}$ ) ( $I_F = 10 \text{ A}$ , $T_C = 125^{\circ}\text{C}$ ) ( $I_F = 20 \text{ A}$ , $T_C = 25^{\circ}\text{C}$ ) ( $I_F = 20 \text{ A}$ , $T_C = 125^{\circ}\text{C}$ ) | V <sub>F</sub> | 0.9<br>0.8<br>1.0<br>0.9 | V    |
| Maximum Instantaneous Reverse Current (Note 1) (Rated dc Voltage, $T_C = 25^{\circ}C$ ) (Rated dc Voltage, $T_C = 125^{\circ}C$ )  | l <sub>R</sub> | 1.0<br>50                | mA   |

#### **DYNAMIC CHARACTERISTICS** (Per Leg)

| Capacitance   | C <sub>T</sub> |     | pF |
|---|----------------|-----|----|
| $(V_{R} = -5.0 \text{ V}, T_{C} = 25^{\circ}\text{C}, \text{ Frequency} = 1.0 \text{ MHz})$ |                | 500 |    |

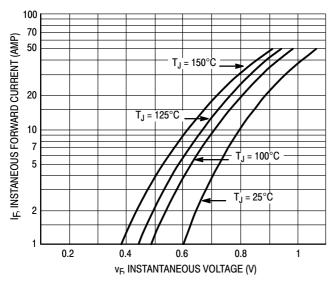
<sup>1.</sup> Pulse Test: Pulse Width = 300 μs, Duty Cycle ≤ 2.0%.

#### **ORDERING INFORMATION**

| Device         | Package                         | Shipping <sup>†</sup>   |
|----------------|---------------------------------|-------------------------|
| MBRB20200CTG   | D <sup>2</sup> PAK<br>(Pb-Free) | 50 Units / Rail         |
| MBRB20200CTT4G | D <sup>2</sup> PAK<br>(Pb-Free) | 800 Units / Tape & Reel |
| SBRB20200CTT4G | D <sup>2</sup> PAK<br>(Pb-Free) | 800 Units / Tape & Reel |

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

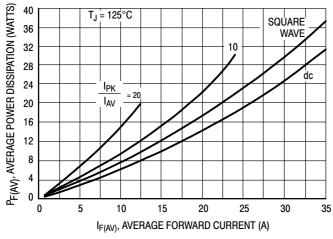
## MBRB20200CTG, SBRB20200CTT4G



10,000  $T_J = 150^{\circ}C$ 1,000 T<sub>J</sub> = 125°C , REVERSE CURRENT (µ.A) <sub>1</sub> = 100°C <u>~</u> 0.1  $T_J = 25^{\circ}C$ 0.01 0 20 40 100 120 180 200 V<sub>R</sub>, REVERSE CURRENT (V)

Figure 1. Typical Forward Voltage (Per Leg)

Figure 2. Typical Reverse Current (Per Leg)



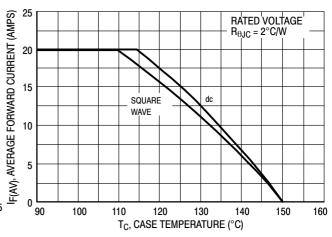
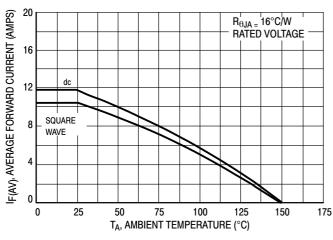


Figure 3. Forward Power Dissipation

Figure 4. Current Derating, Case



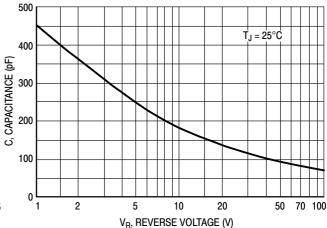


Figure 5. Current Derating, Ambient

Figure 6. Typical Capacitance (Per Leg)

## **MECHANICAL CASE OUTLINE**

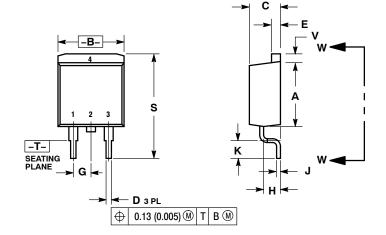




D<sup>2</sup>PAK 3 CASE 418B-04 **ISSUE L** 

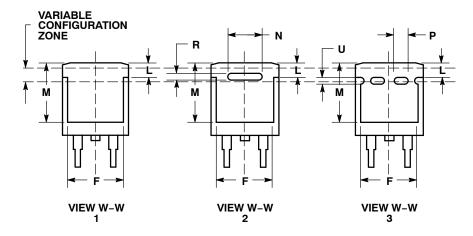
**DATE 17 FEB 2015** 

#### SCALE 1:1



- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
   CONTROLLING DIMENSION: INCH.
- 3. 418B-01 THRU 418B-03 OBSOLETE, NEW STANDARD 418B-04.

|     | INCHES    |       | MILLIMETERS |       |
|-----|-----------|-------|-------------|-------|
| DIM | MIN       | MAX   | MIN         | MAX   |
| Α   | 0.340     | 0.380 | 8.64        | 9.65  |
| В   | 0.380     | 0.405 | 9.65        | 10.29 |
| C   | 0.160     | 0.190 | 4.06        | 4.83  |
| D   | 0.020     | 0.035 | 0.51        | 0.89  |
| Е   | 0.045     | 0.055 | 1.14        | 1.40  |
| F   | 0.310     | 0.350 | 7.87        | 8.89  |
| G   | 0.100     | BSC   | 2.54 BSC    |       |
| Н   | 0.080     | 0.110 | 2.03        | 2.79  |
| 7   | 0.018     | 0.025 | 0.46        | 0.64  |
| K   | 0.090     | 0.110 | 2.29        | 2.79  |
| L   | 0.052     | 0.072 | 1.32        | 1.83  |
| М   | 0.280     | 0.320 | 7.11        | 8.13  |
| N   | 0.197 REF |       | 5.00 REF    |       |
| Р   | 0.079 REF |       | 2.00 REF    |       |
| R   | 0.039 REF |       | 0.99 REF    |       |
| S   | 0.575     | 0.625 | 14.60       | 15.88 |
| ٧   | 0.045     | 0.055 | 1.14        | 1.40  |



STYLE 1: PIN 1. BASE 2. COLLECTOR
3. EMITTER
4. COLLECTOR STYLE 2: PIN 1. GATE 2. DRAIN

3. SOURCE 4. DRAIN

STYLE 3: PIN 1. ANODE 2. CATHODE 3. ANODE 4. CATHODE

STYLE 4:

PIN 1. GATE
2. COLLECTOR
3. EMITTER
4. COLLECTOR

STYLE 5: PIN 1. CATHODE 2. ANODE 3. CATHODE 4. ANODE

STYLE 6: PIN 1. NO CONNECT
2. CATHODE
3. ANODE
4. CATHODE

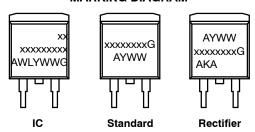
#### **MARKING INFORMATION AND FOOTPRINT ON PAGE 2**

| DOCUMENT NUMBER: | 98ASB42761B          | Electronic versions are uncontrolled except when accessed directly from the Document Repository.<br>Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red. |             |
|------------------|----------------------|---|-------------|
| DESCRIPTION:     | D <sup>2</sup> PAK 3 |   | PAGE 1 OF 2 |

ON Semiconductor and (III) are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

**DATE 17 FEB 2015** 

# GENERIC MARKING DIAGRAM\*



xx = Specific Device Code A = Assembly Location

 WL
 = Wafer Lot

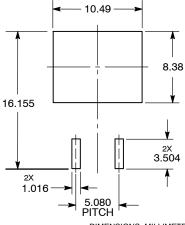
 Y
 = Year

 WW
 = Work Week

 G
 = Pb-Free Package

 AKA
 = Polarity Indicator

#### **SOLDERING FOOTPRINT\***



DIMENSIONS: MILLIMETERS

| DOCUMENT NUMBER: | 98ASB42761B          | Electronic versions are uncontrolled except when accessed directly from the Document Repository<br>Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red. |             |
|------------------|----------------------|--|-------------|
| DESCRIPTION:     | D <sup>2</sup> PAK 3 |  | PAGE 2 OF 2 |

ON Semiconductor and at a trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

<sup>\*</sup>This information is generic. Please refer to device data sheet for actual part marking. Pb–Free indicator, "G" or microdot " ■", may or may not be present.

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and the are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at <a href="www.onsemi.com/site/pdf/Patent-Marking.pdf">www.onsemi.com/site/pdf/Patent-Marking.pdf</a>. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor and see no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and

#### **PUBLICATION ORDERING INFORMATION**

LITERATURE FULFILLMENT:
Email Requests to: orderlit@onsemi.com

ON Semiconductor Website: www.onsemi.com

TECHNICAL SUPPORT North American Technical Support: Voice Mail: 1 800-282-9855 Toll Free USA/Canada Phone: 011 421 33 790 2910

Europe, Middle East and Africa Technical Support:

Phone: 00421 33 790 2910

For additional information, please contact your local Sales Representative